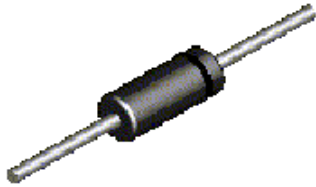


# 1N/FDLL 914/A/B / 916/A/B / 4148 / 4448



DO-35



LL-34

THE PLACEMENT OF THE EXPANSION GAP HAS NO RELATIONSHIP TO THE LOCATION OF THE CATHODE TERMINAL

**COLOR BAND MARKING**

DEVICE	1ST BAND	2ND BAND
FDLL914	BLACK	BROWN
FDLL914A	BLACK	GRAY
FDLL914B	BROWN	BLACK
FDLL916	BLACK	RED
FDLL916A	BLACK	WHITE
FDLL916B	BROWN	BROWN
FDLL4148	BLACK	BROWN
FDLL4448	BROWN	BLACK

## Small Signal Diode

### Absolute Maximum Ratings\*

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	100	V
I <sub>F(AV)</sub>	Average Rectified Forward Current	200	mA
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond	1.0	A
		4.0	A
T <sub>stg</sub>	Storage Temperature Range	-65 to +200	°C
T <sub>J</sub>	Operating Junction Temperature	175	°C

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

**NOTES:**

- 1) These ratings are based on a maximum junction temperature of 200 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## Thermal Characteristics

Symbol	Characteristic	Max	Units
		1N/FDLL 914/A/B / 4148 / 4448	
P <sub>D</sub>	Power Dissipation	500	mW
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	300	°C/W

1N/FDLL 914/A/B / 916/A/B / 4148 / 4448

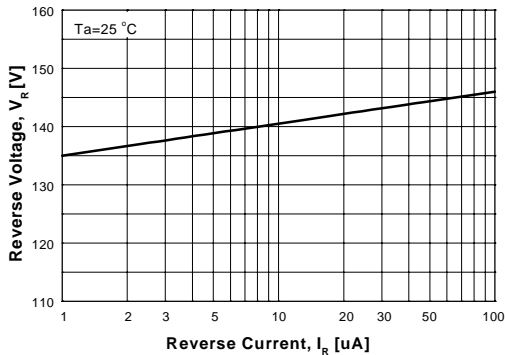
## Small Signal Diode (continued)

### Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

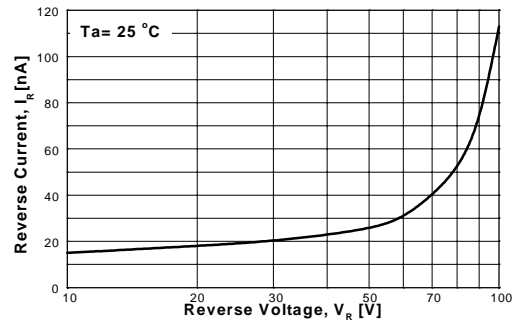
Symbol	Parameter	Test Conditions	Min	Max	Units
$V_R$	Breakdown Voltage	$I_R = 100 \mu\text{A}$ $I_R = 5.0 \mu\text{A}$	100 75		V V
$V_F$	Forward Voltage	<b>1N914B/4448</b> <b>1N916B</b> <b>1N914/916/4148</b> <b>1N914A/916A</b> <b>1N916B</b> <b>1N914B/4448</b>	$I_F = 5.0 \text{ mA}$ $I_F = 5.0 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 20 \text{ mA}$ $I_F = 20 \text{ mA}$ $I_F = 100 \text{ mA}$	620 630 720 730 1.0 1.0 1.0 1.0	mV mV V V V V
$I_R$	Reverse Current	$V_R = 20 \text{ V}$ $V_R = 20 \text{ V}, T_A = 150^\circ\text{C}$ $V_R = 75 \text{ V}$		25 50 5.0	nA $\mu\text{A}$ $\mu\text{A}$
$C_T$	Total Capacitance	<b>1N916A/B/4448</b> <b>1N914A/B/4148</b>	$V_R = 0, f = 1.0 \text{ MHz}$ $V_R = 0, f = 1.0 \text{ MHz}$		2.0 4.0 pF pF
$t_{rr}$	Reverse Recovery Time	$I_F = 10 \text{ mA}, V_R = 6.0 \text{ V (60mA)}$ , $I_{rr} = 1.0 \text{ mA}, R_L = 100\Omega$		4.0	ns

1N/FD/L 914/A/B / 916/A/B / 4148 / 4448

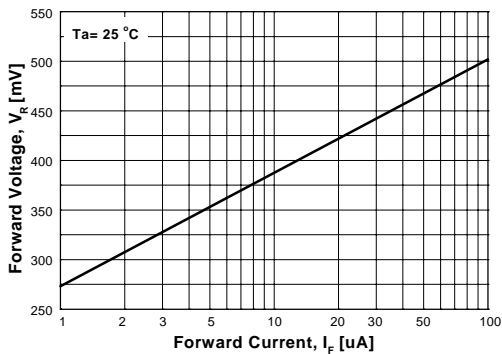
### Typical Characteristics



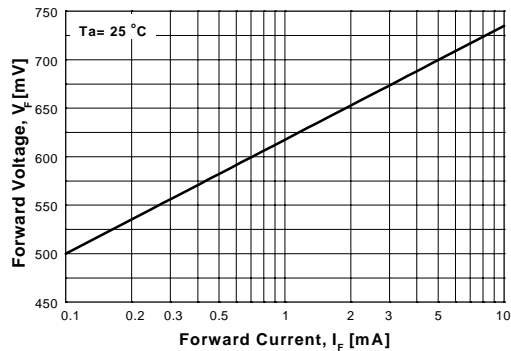
**Figure 1. Reverse Voltage vs Reverse Current**  
BV - 1.0 to 100  $\mu\text{A}$



**Figure 2. Reverse Current vs Reverse Voltage**  
IR - 10 to 100 V  
GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature



**Figure 3. Forward Voltage vs Forward Current**  
VF - 1 to 100  $\mu\text{A}$



**Figure 4. Forward Voltage vs Forward Current**  
VF - 0.1 to 10 mA

Typical Characteristics (continued)

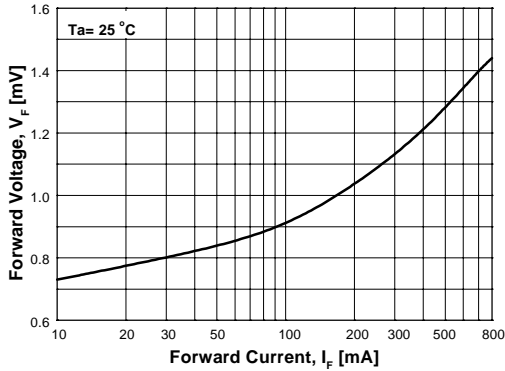


Figure 5. Forward Voltage vs Forward Current  
VF - 10 to 800 mA

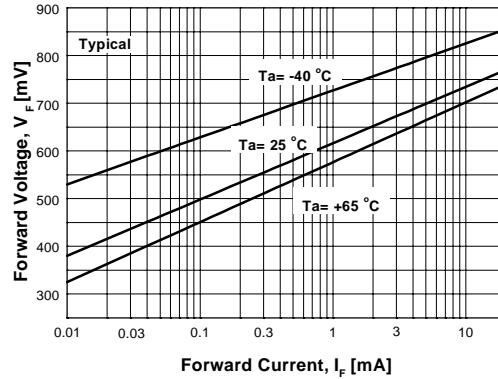


Figure 6. Forward Voltage  
vs Ambient Temperature  
VF - 0.01 - 20 mA (-40 to +65 Deg C)

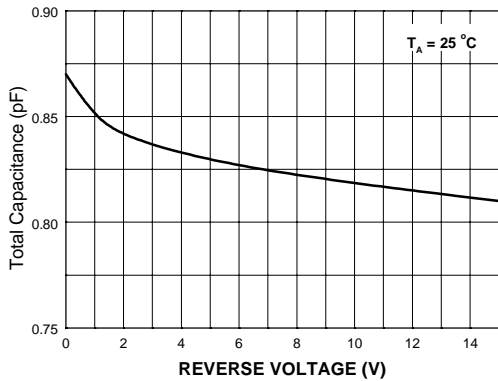


Figure 7. Total Capacitance

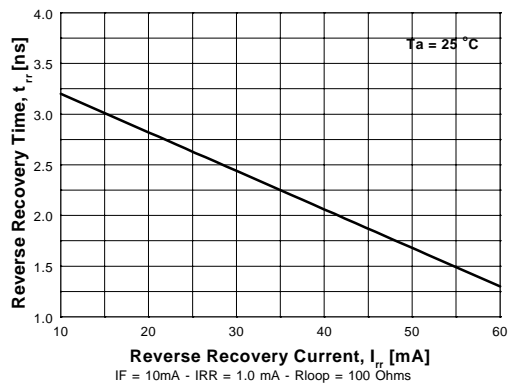


Figure 8. Reverse Recovery Time vs  
Reverse Recovery Current

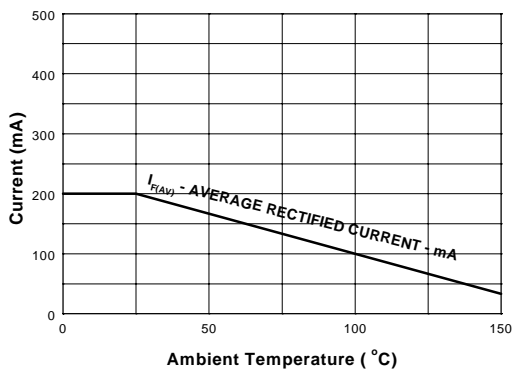


Figure 9. Average Rectified Current ( $I_{F(AV)}$ )  
versus Ambient Temperature ( $T_A$ )

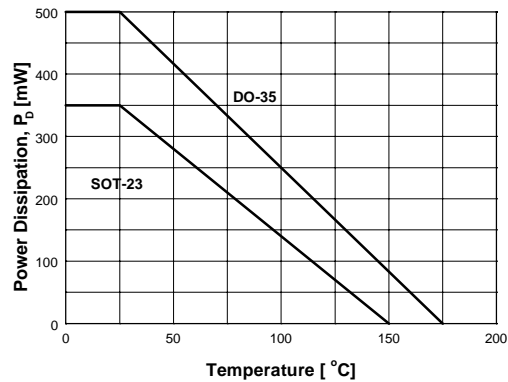


Figure 10. Power Derating Curve